

## THERMO STRING TYPE NTC THERMISTOR

1. Part Numbering (Part Number)

(Pa <u>N&gt;</u> Produ		15 Chip dimensions		202 Resistance	E Resistance tolerance	A Lead wire specifications	5 Lead wire forming	B Packaging	025 Dimensions (Full length)
2. P	2. Part No. and ratings								
	Murata P/N (*1)		esistance value at.25°C	B-constant 25/50°C		Operating current for sensor (mA) (*2,*3)	tempera	erating ture range °C)	
	NXRT15XM202E	A5B***	2k Ω+/-3%	3500K	C +/-1%	0.36			
	NXRT15XV502FA	\5B***	5k Ω+/-1%	3936K	C +/-1%	0.22			
		A CD+++	101-0+/ 10/	00001/	/ 40/	0.40			

Murata P/N (*1)	Resistance value at.25℃	B-constant 25/50°C	Operating current for sensor (mA) (*2,*3)	Operating temperature range (°C)
NXRT15XM202EA5B***	2k Ω+/-3%	3500K +/-1%	0.36	
NXRT15XV502FA5B***	5k Ω+/-1%	3936K +/-1%	0.22	
NXRT15XH103FA5B***	10k Ω+/-1%	3380K +/-1%	0.16	
NXRT15XV103FA5B***	10k Ω+/-1%	3936K +/-1%	0.16	-40~+125
NXRT15WB333JA5B***	33k Ω+/-5%	4050K +/-3%	0.08	
NXRT15WB473FA5B***	47k Ω+/-1%	4050K +/-1%	0.07	
NXRT15WF104FA5B***	100k Ω+/-1%	4250K +/-1%	0.05	

Thermal dissipation constant

Rated electric power

Thermal time constant

2.6mW/°C (\*4)

13mW (\*2,4)

4sec. (25°C to 50°C in air)

\*1: \*\*\* means the full length (Example : 045=45mm) 25~45mm Interval 5mm.

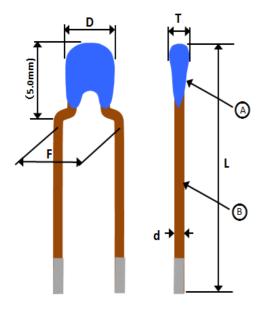
\*2 : Measured at 25°C in still air, as a single unit without mounting.

\*3 : Operating current rises for sensor rises thermistor's temperature by 0.1°C. Please regard self heat of the Chip Radial.

\*4: Too rapid temperature rising, however, may cause any unexpected failures on your circuit. Please do not apply high electric power in short time.



3. Construction and dimensions (in mm)



	Dimensions (mm)	Notes
D	4mm Max.	Resin width
Т	2mm Max.	Resin thickness
L	25 to 45±1mm (5mm step)	Full length
F	2.5±1mm	lead spacing
d	0.46±0.05 mm	Lead wire diameter
$\bigcirc$	-	Epoxy resin
®	-	Copper lead wire with polyurethane coat

\* The NTC thermistor in epoxy resin is soldered by SnAgCu

4. Quantity (Standard Quantity) 500pcs. ∕ unit bag.



#### Notice for use

# ⚠ Special Caution

1. This product is using the solder of about 220 °C of melting points. Please perform soldering on a condition not melt the solder in resin head. (260 degrees Celsius, less than 10 seconds and more than 25mm in full length of the product)

When I am the worst, heat reaches the element part from a lead terminal part, and a solder of our product element region melts it, and there are fear of break of wire, or short circuit.

- Please do a quality rating enough by a real machine when bonding, the resin molding, and the resin coating, etc. are processed to this product. And, please use it after confirming it is unquestionable. Especially, please do not process it under the high temperature and the high pressure. The stress occurs because of the amount, the resin thickness, bias, and the temperature change of the fabricating materials (bonding material, molding resin, and coating material etc.) And, there is a possibility to generate the crack and the characteristic degradation by the stress.
- 3. If strong tension against a lead or aggressiveness pressure strong against a resin part is applied, a resin part and an internal element will break or crack. In addition, the risk of the break or crack increases more because resin might soften in a high temperature, the pressurized state. Please avoid use in the state where it was pressurized.

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- 1. Applying the power exceeding rated Electric Power may result to deterioration of characteristics, destruction of product or in the worst case, to catching fire. Do not apply the power exceeding rated Electric Power.
- 2.Resin of this product is not waterproofing.

Do not use NTC Thermistor under the following environments because all these factors can deteriorate the characteristics of product or can cause the failures and the burning-out. place with splashed water or under high humidity with dewing.

3. Exposing the NTC Thermistor to the following environment may result to deterioration of characteristics. ①Corrosive gas or deoxidizing gas (Cl<sub>2</sub>,H<sub>2</sub>S,NH<sub>3</sub>,SO<sub>X</sub>,NO<sub>X</sub> etc.)

②Volatile, flammable gas
③Dusty place
④Low or high air pressure
⑤Salt water, oil, chemical liquid and solvent.
⑥Vibratile place
⑦Other place equivalent to the above ① through ⑥

4. Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

①Aircraft equipment ②Aerospace equipment ③Undersea equipment ④Power plant control equipment ⑤Medical equipment ⑥Transportation equipment(vehicles, trains, ships, etc.)

⑦Traffic signal equipment
 ⑧Disaster prevention/crime prevention equipment
 ⑨Data-processing equipment
 ⑨Application of similar complexity and/or reliability requirements to the applications

Application of similar complexity and/or reliability requirements to the applications listed in

5. Addition of fail safe function

Please provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product.

### Murata Manufacturing Co.,Ltd.

CT-008E' JWB01BU-0098

This information may be changed without a previous notice.



Notice

- 1.Use this product within the specified temperature range. Higher temperature may cause deterioration of the characteristics or the material guality of this product.
- 2. To keep solderbility and characteristic of product from declining, following storage condition is recommended.

<ol> <li>Storage condition</li> </ol>	Temperature	:-10°C∼+40°C					
	Humidity	: less than 75% RH (not dewing condition)					
2 Term	Please use this proc	duct within 1 year after shipment					
	by first-in first-out sto	ocking system.					
③Handling after sea	l open						
After unpack aging of the minimum package, reseal it promptly or store it inside a sealed container with a c							
agent.							

④Place

Do not store this product in corrosive gas (SOx, Cl etc.) or under sun-light.

- 3. Do not touch the resin head directly by solder iron. It may cause the melt of solder in resin head.
- 4. The ceramic element of this product is fragile, and care must be taken not to load a excessive press-force or not to give a shock at handling. Such forces may cause cracking or chipping.
- 5. Do not apply an excessive force to the lead. Otherwise, it may cause break off of junction between lead and element, or may crack element. Therefore, hold of element side lead wire is recommended when lead wire is bent or cut.
- 6. Please do not do the processing bending and straightening the quinqueparts of the lead. When such a processing is necessary, please talk to us.

### \land Note

- 1.Please make sure that the component is evaluated against the specification when it is mounted to your product. This evaluation will be needed to confirm any unforeseen hazardous situation which is not observed in the evaluation of component.
- 2.All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 3.We consider it not appropriate to include any terms and conditions with regard to the business transaction in the product specifications, drawings or other technical documents. Therefore, if your technical documents as above include such terms and conditions such as warranty clause, product liability clause, or intellectual property infringement liability clause, they will be deemed to be invalid.